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SPECIFICATION

| | | |
|--------------|---|---|
| Part No. | : | PA.22A |
| Product Name | : | Dielectric PIFA Antenna |
| Description | : | Tri-band - 880~960 MHz, 1710~1990 MHz, 0dB Gain Size: 29.8mm*6mm*5mm RoHS Compliant |



1.Scope

This specification is for a Tri-band GSM miniature PIFA (Dielectric Planar Inverted-F Type Antenna) (DPA™) Antenna for internal SMT mounting.

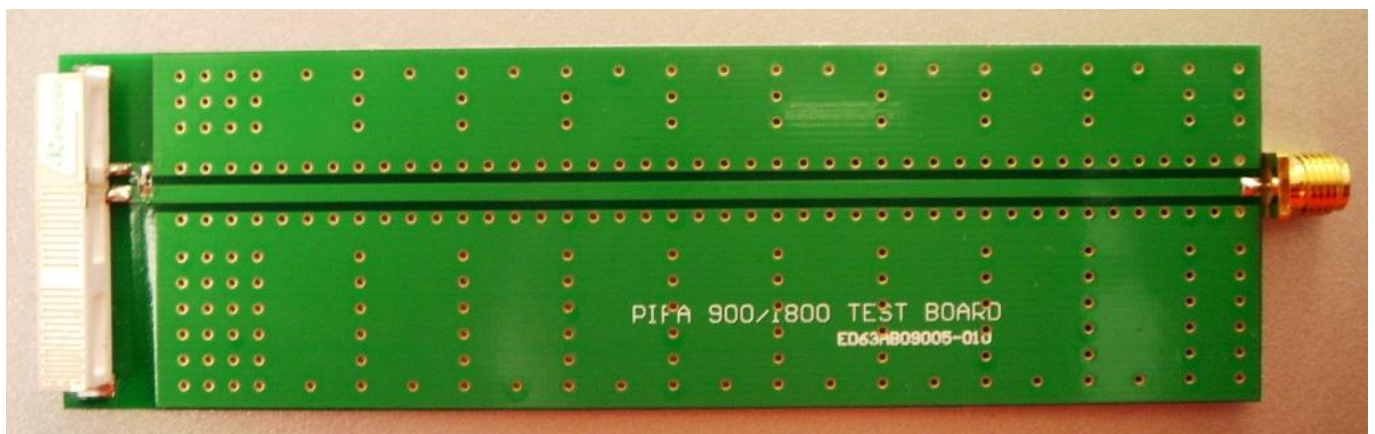
Note: The antenna also shows a response at 850MHz which means the antenna can also be defined on quad-band, depending on the target specification for the device itself.

2.Electrical Specifications

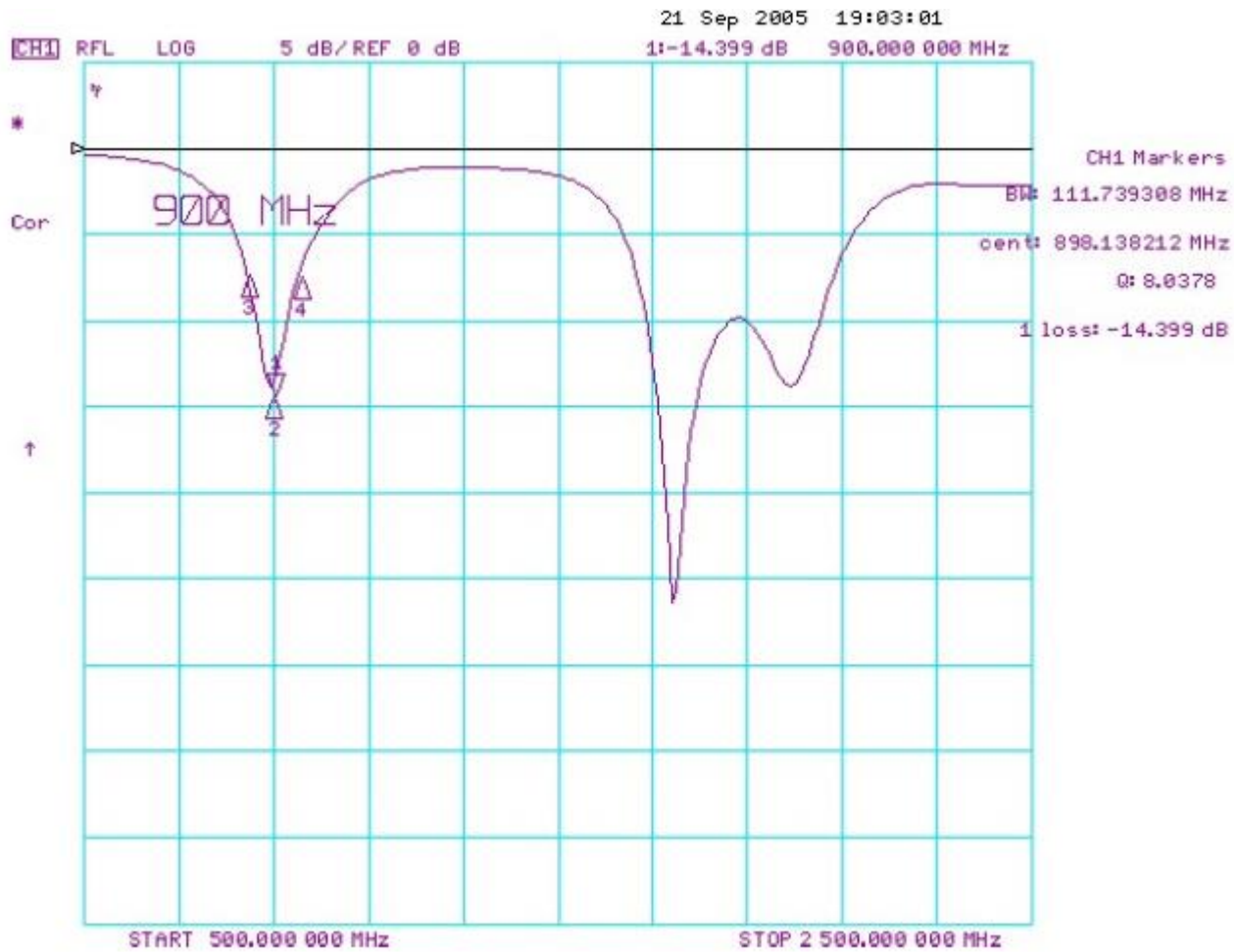
The antenna has the electrical characteristics given in Table 1 under the Taoglas standard installation conditions as shown in the Evaluation Board (Figure

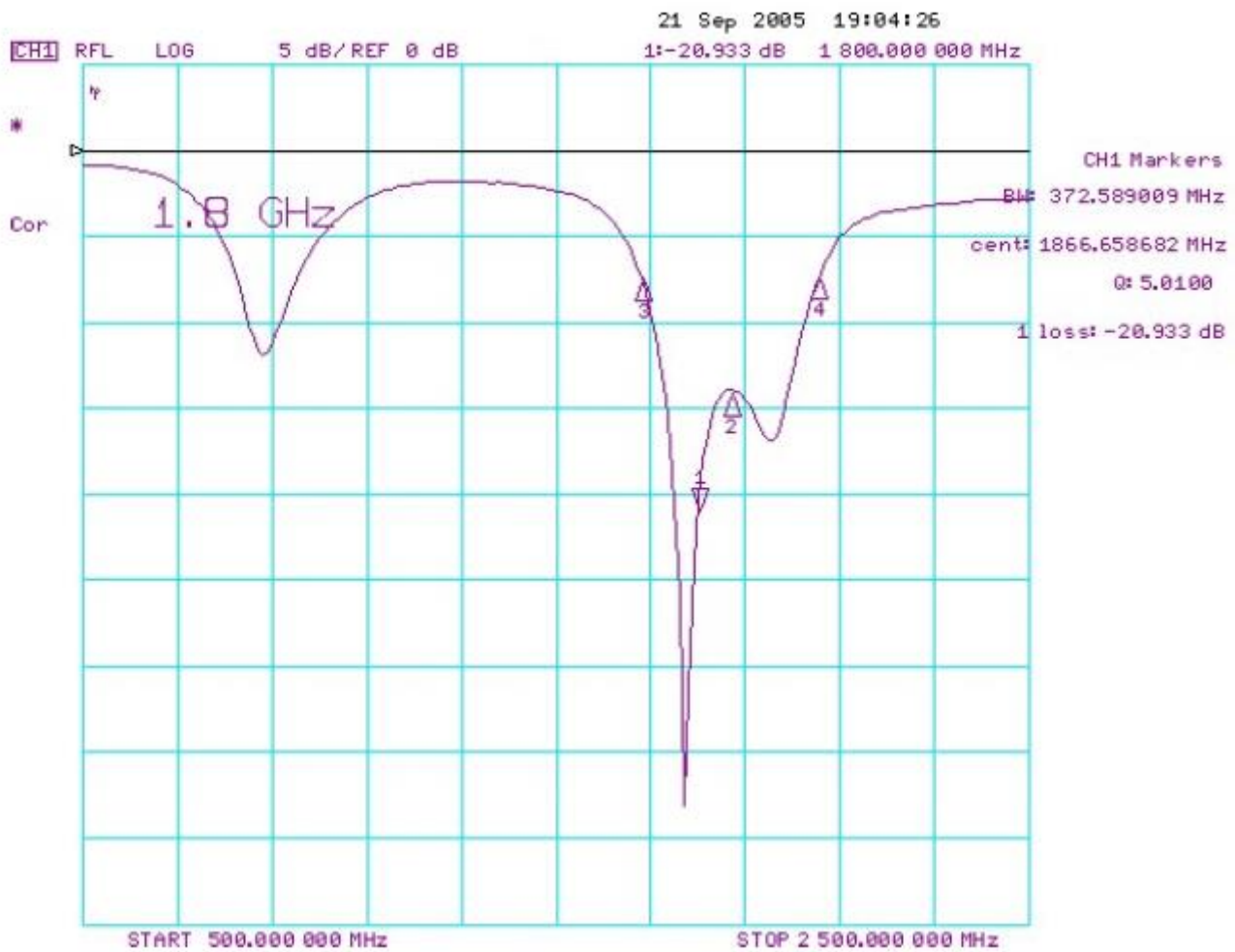
| No. | Parameter | Specification |
|-----|-----------------------|---|
| 1 | Frequency | 880~960 MHz , 1710~1990 MHz |
| 2 | Dimensions | 29.8*6.0*5.0 mm |
| 3 | Impedance | 50 Ω |
| 4 | VSWR | 2.5 max (depends on environment) |
| 5 | Polarization | Linear |
| 6 | Operating Temperature | -40~85°C |
| 7 | Termination | Ag (Environmentally Friendly Lead-Free) |

*Data is measured on Taoglas Evaluation Board (reference ground plane) pictured below



2.1 S11 Response Curve





Radiation patterns also available (measured in free space and on evaluation board)

2.2 Gain and Efficiency

GSM900

| | Frequency (MHz) | Peak Gain (dBi) | Efficiency (%) |
|----|--------------------|--------------------|-------------------|
| TX | 880.2 | -3.65 | 21.09 |
| | 890.2 | -2.73 | 26.25 |
| | 902.4 | -2.28 | 31.23 |
| | 914.8 | -2.04 | 35.24 |
| RX | 925.2 | -1.96 | 37.02 |
| | 935.2 | -2.54 | 33.33 |
| | 947.4 | -2.96 | 31.17 |
| | 959.8 | -3.16 | 29.47 |

GSM1800

| | Frequency (MHz) | Peak Gain (dBi) | Efficiency (%) |
|----|----------------------------|----------------------------|---------------------------|
| TX | 1710.2 | 2.28 | 60.63 |
| | 1747.6 | 2.35 | 61.53 |
| | 1784.8 | 2.58 | 60.77 |
| RX | 1805.2 | 2.32 | 56.67 |
| | 1842.6 | 2.43 | 56.31 |
| | 1879.8 | 2.59 | 58.69 |

GSM1900

| | Frequency (MHz) | Peak Gain (dBi) | Efficiency (%) |
|----|----------------------------|----------------------------|---------------------------|
| TX | 1850.2 | 2.48 | 56.95 |
| | 1880.0 | 2.60 | 58.75 |
| | 1909.8 | 2.12 | 52.79 |
| RX | 1930.2 | 2.01 | 52.02 |
| | 1960.0 | 1.31 | 47.26 |
| | 1989.8 | 0.30 | 38.62 |

GSM900

| | Frequency (GHz) | Plane | Average Gain (dBi) |
|----|-----------------|----------|--------------------|
| TX | 880.2 | XY plane | -7.133 |
| | | YZ plane | -9.766 |
| | | XZ plane | -6.101 |
| | 890.2 | XY plane | -5.968 |
| | | YZ plane | -8.845 |
| | | XZ plane | -5.126 |
| | 902.4 | XY plane | -4.898 |
| | | YZ plane | -8.892 |
| | | XZ plane | -4.350 |
| RX | 914.8 | XY plane | -4.077 |
| | | YZ plane | -7.477 |
| | | XZ plane | -3.865 |
| | 925.2 | XY plane | -3.599 |
| | | YZ plane | -7.202 |
| | | XZ plane | -3.732 |
| | 935.2 | XY plane | -3.802 |
| | | YZ plane | -7.648 |
| | | XZ plane | -4.290 |
| | 947.4 | XY plane | -3.788 |
| | | YZ plane | -7.843 |
| | | XZ plane | -4.579 |
| | 959.8 | XY plane | -3.801 |
| | | YZ plane | -7.913 |
| | | XZ plane | -5.187 |

GSM1800

| | Frequency (GHz) | Plane | Average Gain (dBi) |
|----|-----------------|----------|--------------------|
| TX | 1710.2 | XY plane | -2.648 |
| | | YZ plane | -4.661 |
| | | XZ plane | -1.687 |
| | 1747.6 | XY plane | -2.529 |
| | | YZ plane | -4.696 |
| | | XZ plane | -1.207 |
| | 1784.8 | XY plane | -2.685 |
| | | YZ plane | -4.687 |
| | | XZ plane | -0.888 |
| RX | 1805.2 | XY plane | -3.193 |
| | | YZ plane | -4.911 |
| | | XZ plane | -1.105 |
| | 1842.6 | XY plane | -3.468 |
| | | YZ plane | -4.753 |
| | | XZ plane | -1.145 |
| | 1879.8 | XY plane | -3.745 |
| | | YZ plane | -4.131 |
| | | XZ plane | -1.430 |

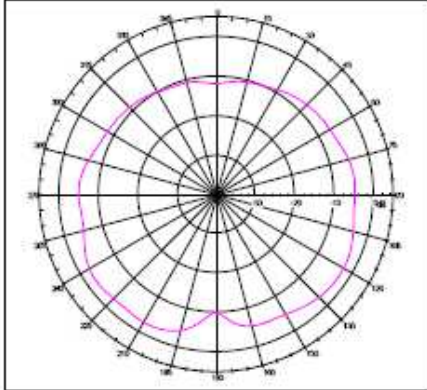
GSM1900

| | Frequency (GHz) | Plane | Average Gain (dBi) |
|----|-----------------|----------|--------------------|
| TX | 1850.2 | XY plane | -3.511 |
| | | YZ plane | -4.649 |
| | | XZ plane | -1.147 |
| | 1880.0 | XY plane | -3.746 |
| | | YZ plane | -4.124 |
| | | XZ plane | -1.435 |
| | 1909.8 | XY plane | -4.683 |
| | | YZ plane | -4.228 |
| | | XZ plane | -2.525 |
| RX | 1930.2 | XY plane | -5.539 |
| | | YZ plane | -4.270 |
| | | XZ plane | -3.257 |
| | 1960.0 | XY plane | -6.444 |
| | | YZ plane | -4.441 |
| | | XZ plane | -4.126 |
| | 1989.8 | XY plane | -8.068 |
| | | YZ plane | -5.359 |
| | | XZ plane | -5.477 |

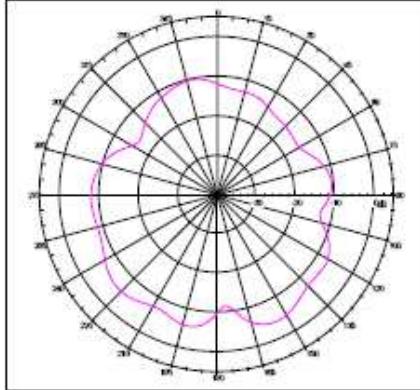
GSM900

Frequency :880.2 MHz

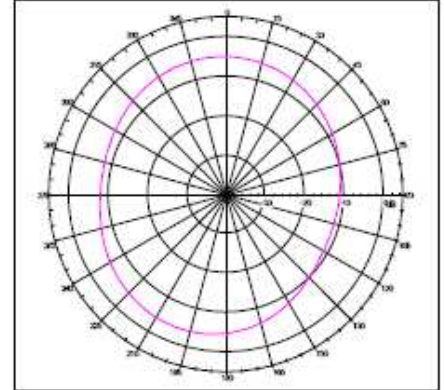
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain:-3.65 dBi, Total Radiating Efficiency: 21.09% @880.20 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain:-3.65 dBi, Total Radiating Efficiency: 21.09% @880.20 GHz

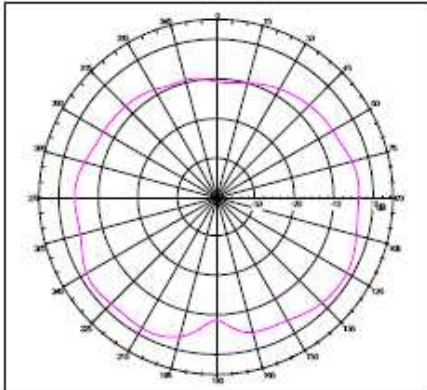


Far-field Power Distribution on X-Y Plane
Gain:-3.65 dBi, Total Radiating Efficiency: 21.09% @880.20 GHz

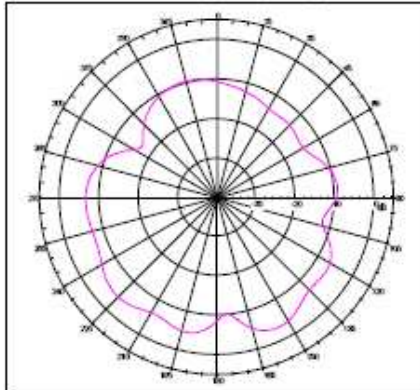


Frequency :890.2 MHz

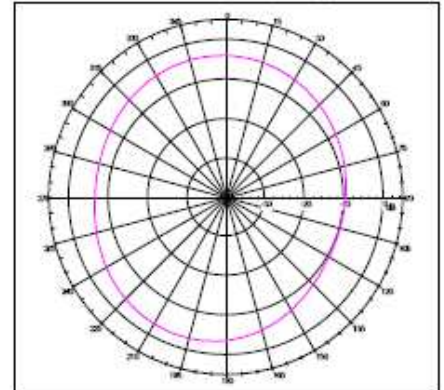
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain:-3.73 dBi, Total Radiating Efficiency: 26.25% @890.20 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain:-3.73 dBi, Total Radiating Efficiency: 26.25% @890.20 GHz

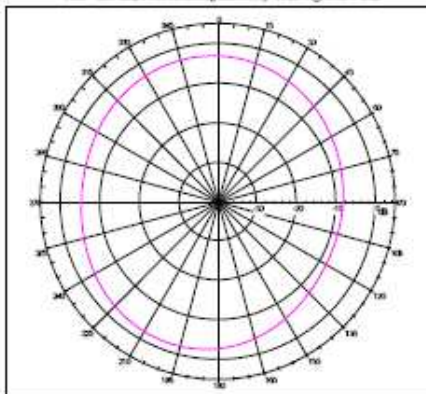


Far-field Power Distribution on X-Y Plane
Gain:-3.73 dBi, Total Radiating Efficiency: 26.25% @890.20 GHz

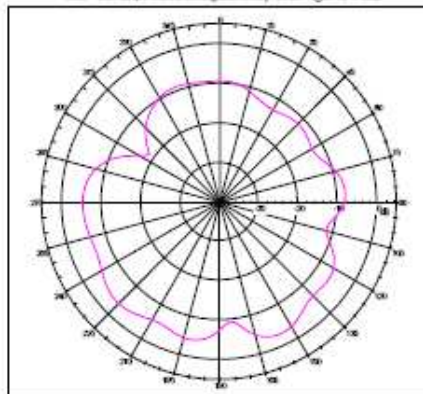


Frequency :902.4MHz

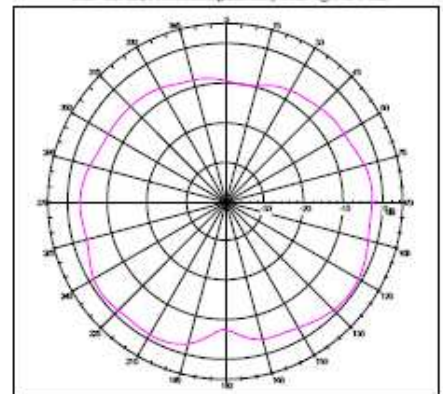
Far-field Power Distribution on X-Y Plane
Gain:-2.28 dBi, Total Radiating Efficiency: 31.23% @902.40 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain:-2.28 dBi, Total Radiating Efficiency: 31.23% @902.40 GHz

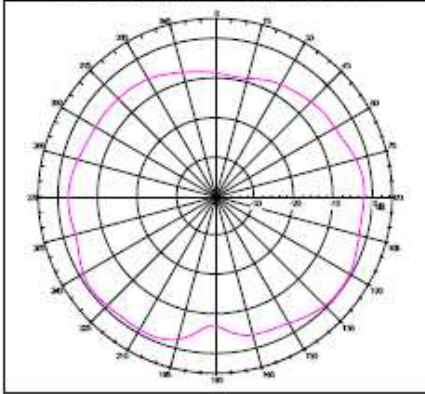


Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain:-2.28 dBi, Total Radiating Efficiency: 31.23% @902.40 GHz

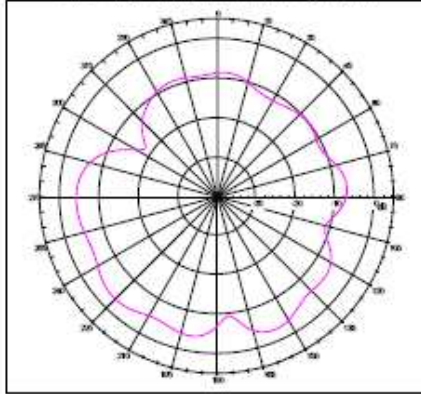


Frequency :914.8MHz

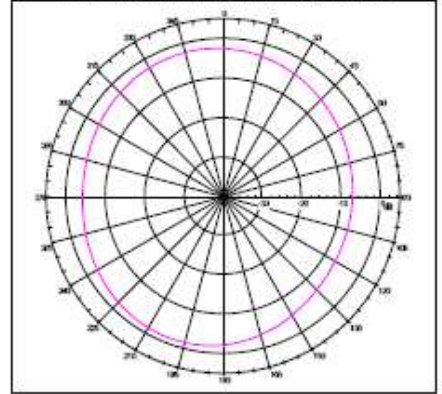
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain:-2.04 dBi, Total Radiating Efficiency: 35.24% @914.80 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain:-2.04 dBi, Total Radiating Efficiency: 35.24% @914.80 GHz

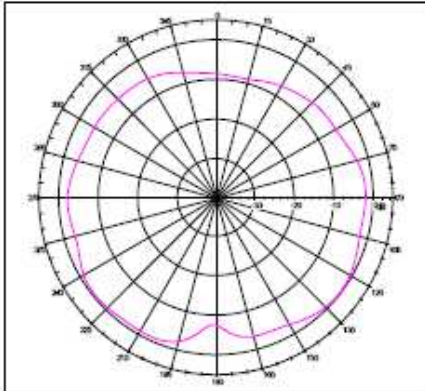


Far-field Power Distribution on X-Y Plane
Gain:-2.04 dBi, Total Radiating Efficiency: 35.24% @914.80 GHz

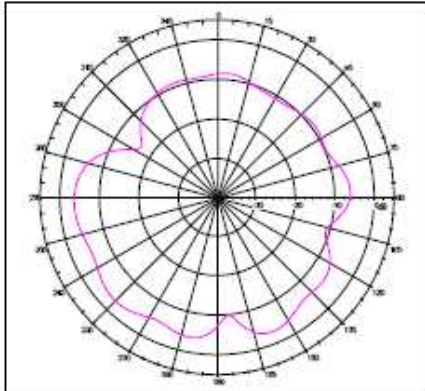


Frequency :925.2MHz

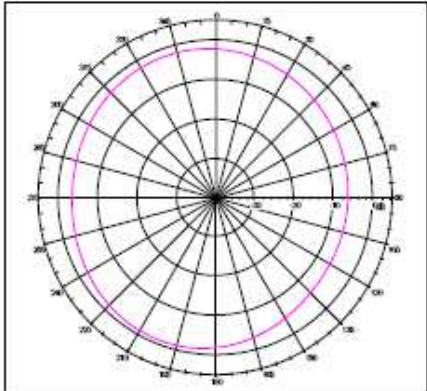
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain:-1.96 dBi, Total Radiating Efficiency: 37.02% @925.20 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain:-1.96 dBi, Total Radiating Efficiency: 37.02% @925.20 GHz

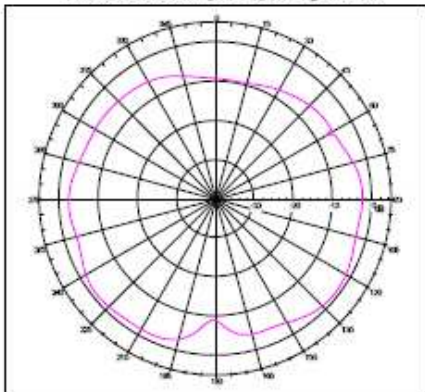


Far-field Power Distribution on X-Y Plane
Gain:-1.96 dBi, Total Radiating Efficiency: 37.02% @925.20 GHz

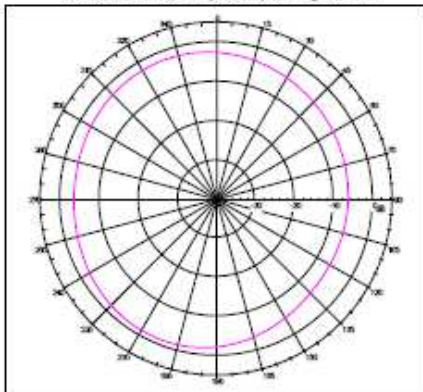


Frequency :935.2MHz

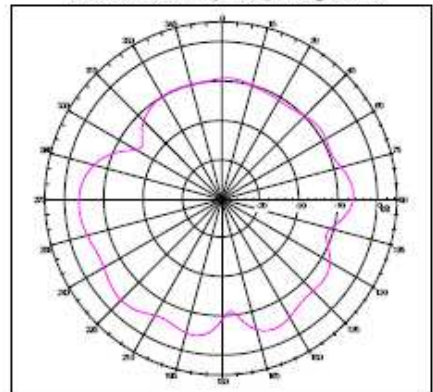
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain:-2.54 dBi, Total Radiating Efficiency: 33.33% @935.20 GHz



Far-field Power Distribution on X-Y Plane
Gain:-2.54 dBi, Total Radiating Efficiency: 33.33% @935.20 GHz

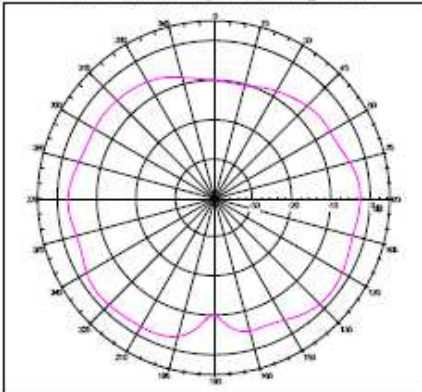


Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain:-2.54 dBi, Total Radiating Efficiency: 33.33% @935.20 GHz

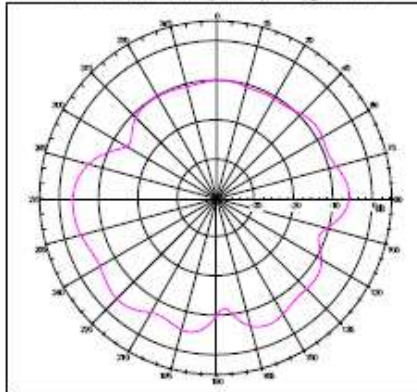


Frequency :947.4MHz

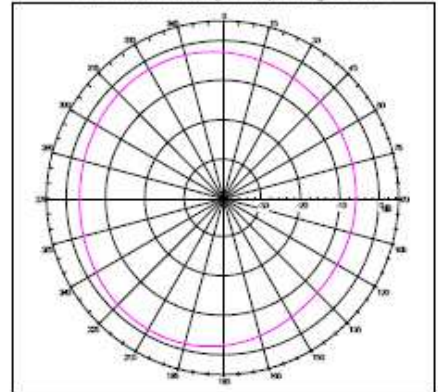
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=-2.96 dBi, Total Radiating Efficiency: 31.17% @947.40 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=-2.96 dBi, Total Radiating Efficiency: 31.17% @947.40 GHz

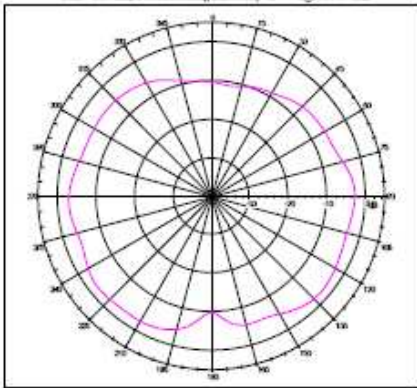


Far-field Power Distribution on X-Y Plane
Gain=-2.96 dBi, Total Radiating Efficiency: 31.17% @947.40 GHz

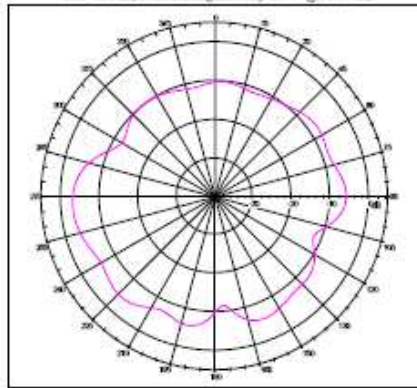


Frequency :959.8MHz

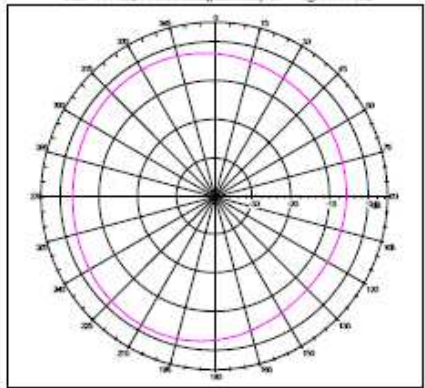
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=-3.16 dBi, Total Radiating Efficiency: 29.47% @959.80 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=-3.16 dBi, Total Radiating Efficiency: 29.47% @959.80 GHz



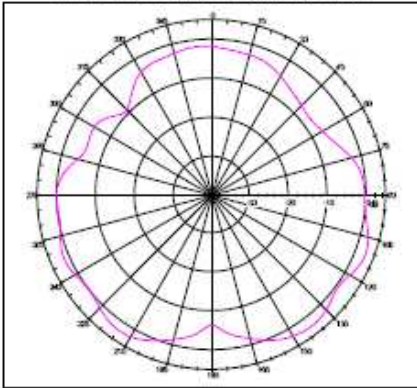
Far-field Power Distribution on X-Y Plane
Gain=-3.16 dBi, Total Radiating Efficiency: 29.47% @959.80 GHz



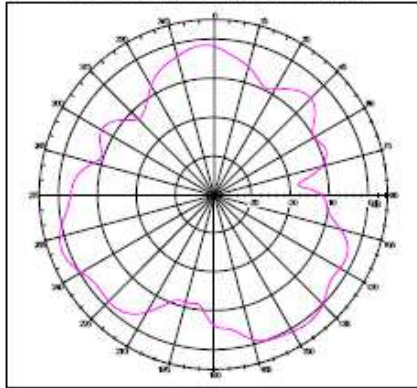
GSM1800

Frequency :1710.2 MHz

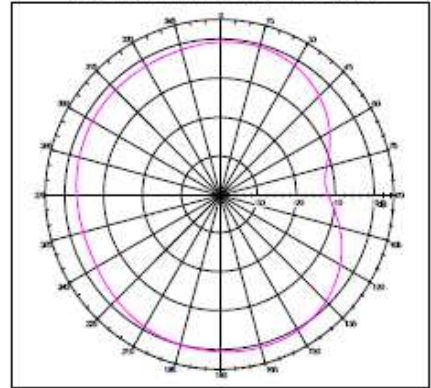
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.28 dBi; Total Radiating Efficiency: 60.67% @ 71020 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.28 dBi; Total Radiating Efficiency: 60.67% @ 71020 GHz

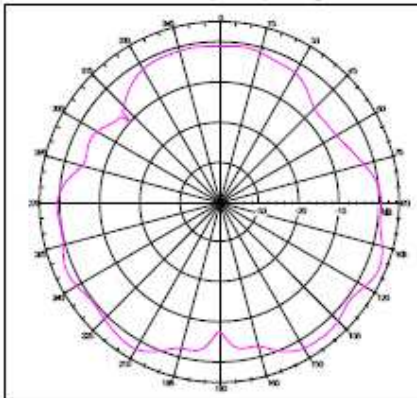


Far-field Power Distribution on X-Y Plane
Gain=2.28 dBi; Total Radiating Efficiency: 60.67% @ 71020 GHz

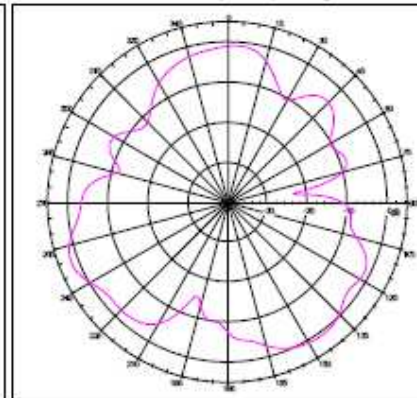


Frequency :1747.6 MHz

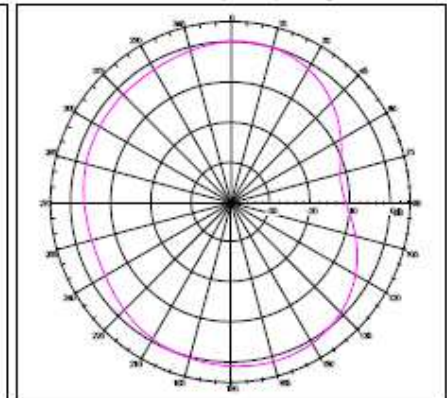
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.35 dBi; Total Radiating Efficiency: 61.53% @ 74760 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.35 dBi; Total Radiating Efficiency: 61.53% @ 74760 GHz

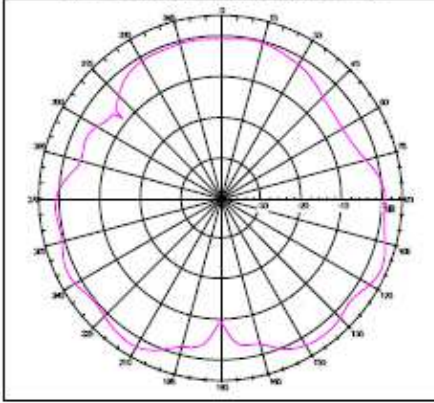


Far-field Power Distribution on X-Y Plane
Gain=2.35 dBi; Total Radiating Efficiency: 61.53% @ 74760 GHz

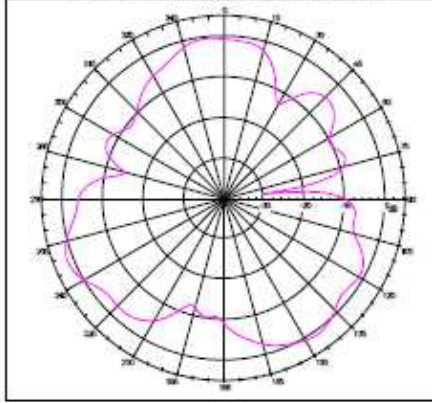


Frequency :1784.8 MHz

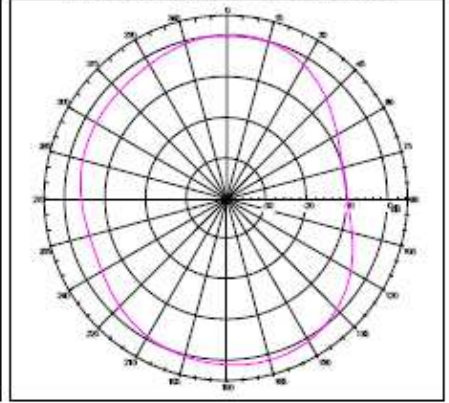
Far-field Power Distribution on X-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.58 dBi, Total Radiating Efficiency: 60.77% @ 1784.8 GHz



Far-field Power Distribution on Y-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.58 dBi, Total Radiating Efficiency: 60.77% @ 1784.8 GHz

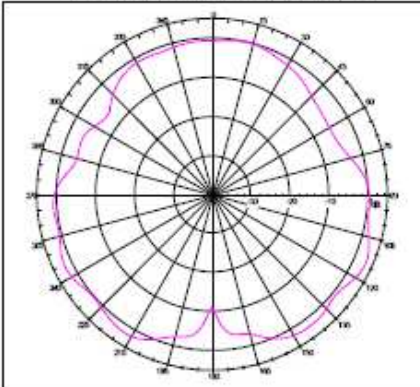


Far-field Power Distribution on X-Y Plane
Gain=2.58 dBi, Total Radiating Efficiency: 60.77% @ 1784.8 GHz

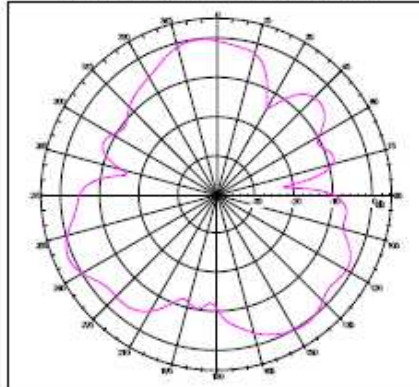


Frequency :1805.2 MHz

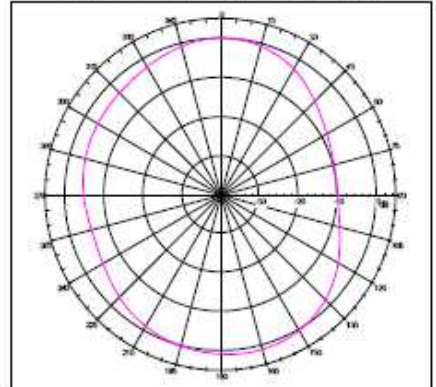
Far-field Power Distribution on X-Z Plane(H-Plane of L3 Pol Sense)
Gain=2.32 dBi, Total Radiating Efficiency: 56.67% @ 1805.2 GHz



Far-field Power Distribution on Y-Z Plane(E-Plane of L3 Pol Sense)
Gain=2.32 dBi, Total Radiating Efficiency: 56.67% @ 1805.2 GHz

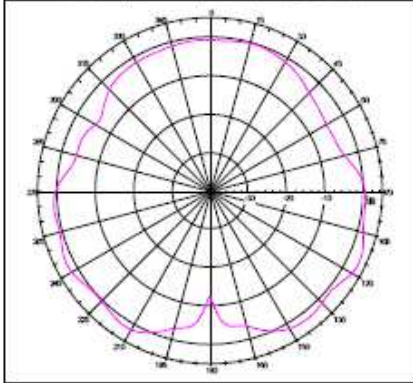


Far-field Power Distribution on X-Y Plane
Gain=2.32 dBi, Total Radiating Efficiency: 56.67% @ 1805.2 GHz

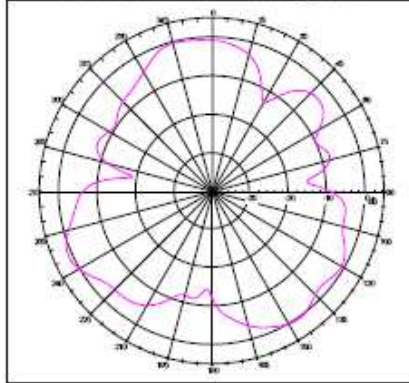


Frequency :1842.6 MHz

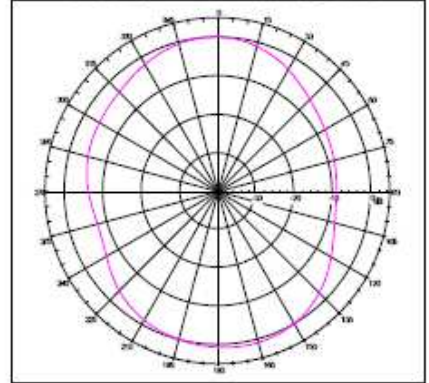
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=2.42 dBi, Total Radiating Efficiency: 56.31% @ 8.4250 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=2.42 dBi, Total Radiating Efficiency: 56.31% @ 8.4250 GHz

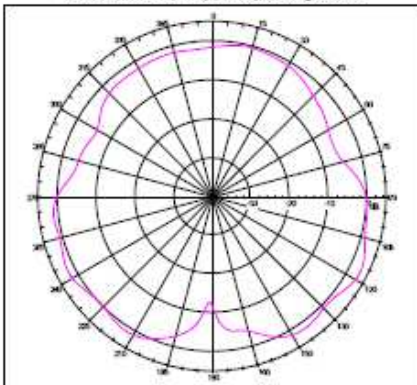


Far-field Power Distribution on X-Y Plane
Gain=2.42 dBi, Total Radiating Efficiency: 56.31% @ 8.4250 GHz

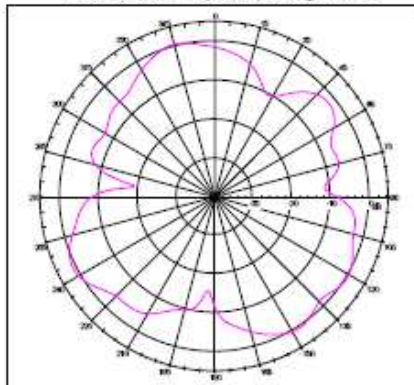


Frequency :1879.8 MHz

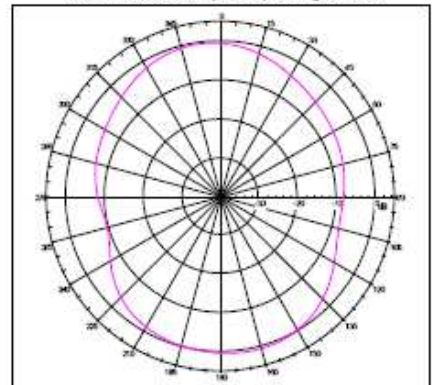
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=2.59 dBi, Total Radiating Efficiency: 58.69% @ 8.7980 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=2.59 dBi, Total Radiating Efficiency: 58.69% @ 8.7980 GHz



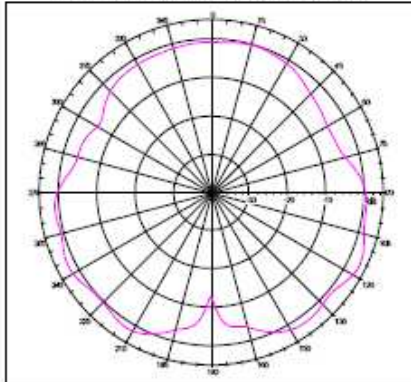
Far-field Power Distribution on X-Y Plane
Gain=2.59 dBi, Total Radiating Efficiency: 58.69% @ 8.7980 GHz



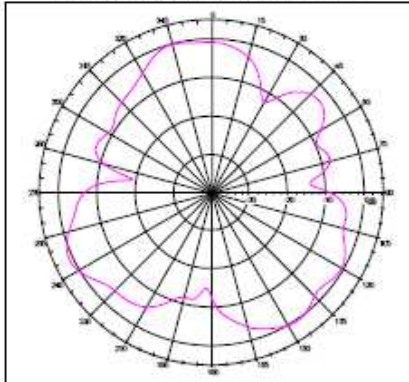
GSM1900

Frequency :1850.2 MHz

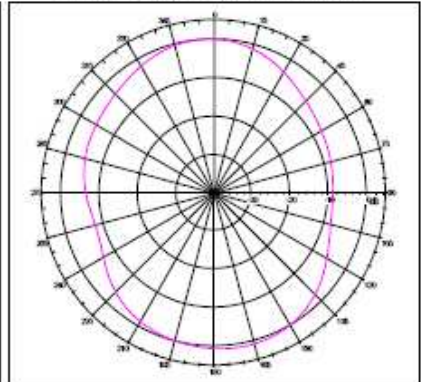
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=2.48 dBi, Total Radiating Efficiency: 56.99% @ 1850.2 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=2.48 dBi, Total Radiating Efficiency: 56.99% @ 1850.2 GHz

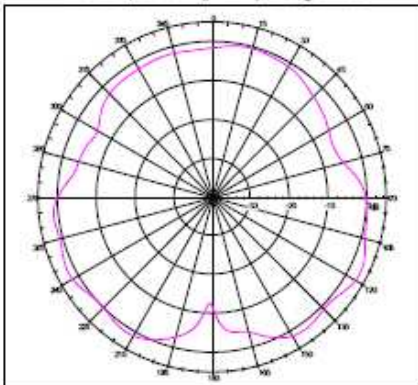


Far-field Power Distribution on X-Y Plane
Gain=2.48 dBi, Total Radiating Efficiency: 56.99% @ 1850.2 GHz

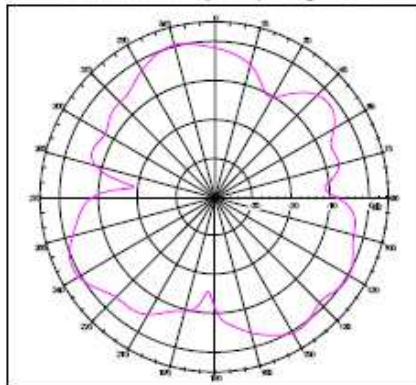


Frequency :1880.0 MHz

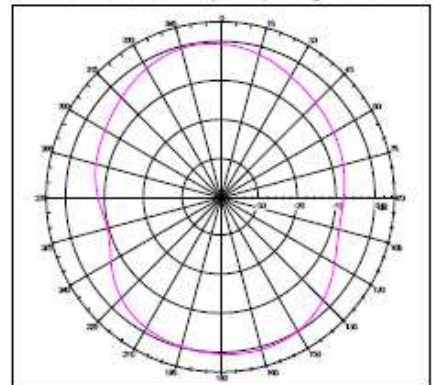
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=2.65 dBi, Total Radiating Efficiency: 58.79% @ 1880.0 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=2.65 dBi, Total Radiating Efficiency: 58.79% @ 1880.0 GHz

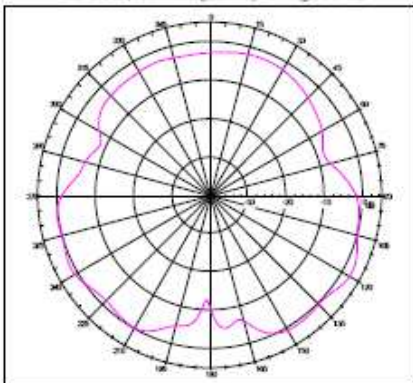


Far-field Power Distribution on X-Y Plane
Gain=2.65 dBi, Total Radiating Efficiency: 58.79% @ 1880.0 GHz

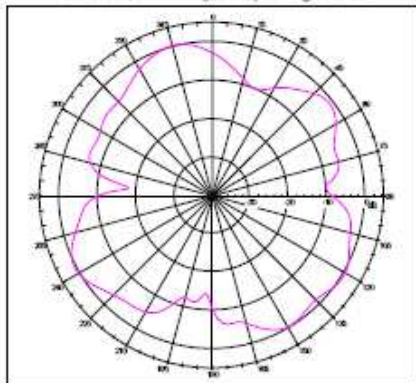


Frequency :1909.8 MHz

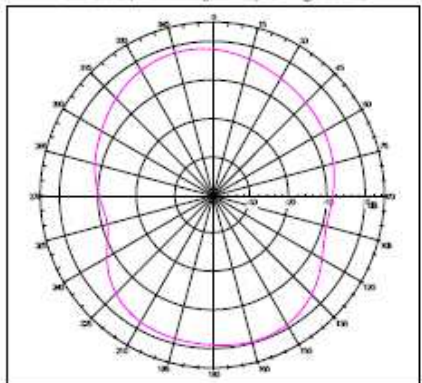
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=2.12 dBi, Total Radiating Efficiency: 52.79% @ 1909.8 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=2.12 dBi, Total Radiating Efficiency: 52.79% @ 1909.8 GHz

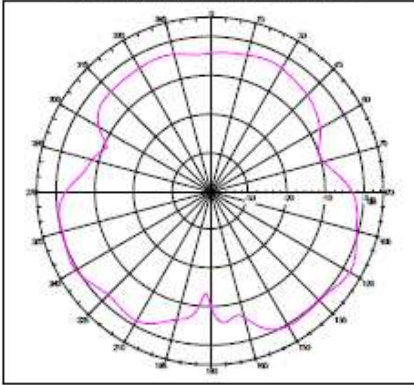


Far-field Power Distribution on X-Y Plane
Gain=2.12 dBi, Total Radiating Efficiency: 52.79% @ 1909.8 GHz

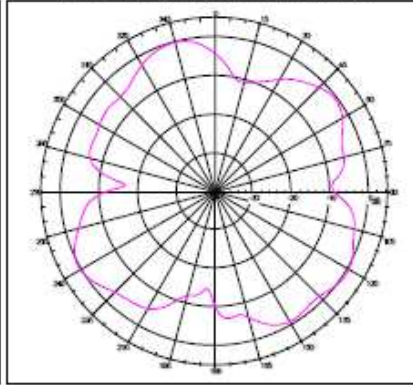


Frequency : 1930.2 MHz

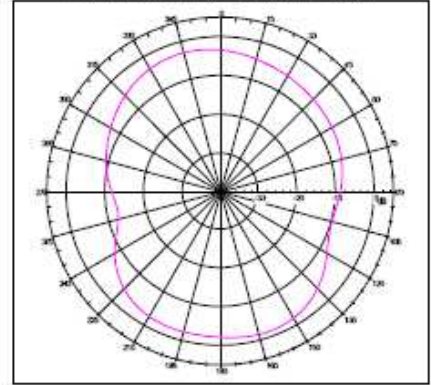
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=1.80 dBi, Total Radiating Efficiency: 50.11% @ 50000 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=1.80 dBi, Total Radiating Efficiency: 50.11% @ 50000 GHz

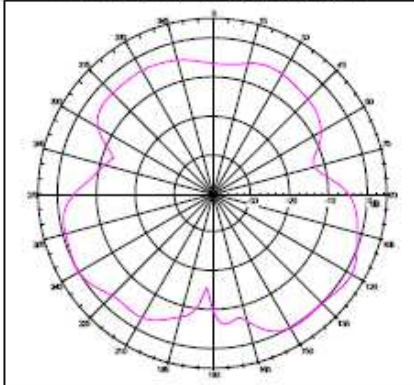


Far-field Power Distribution on X-Y Plane
Gain=1.80 dBi, Total Radiating Efficiency: 50.11% @ 50000 GHz

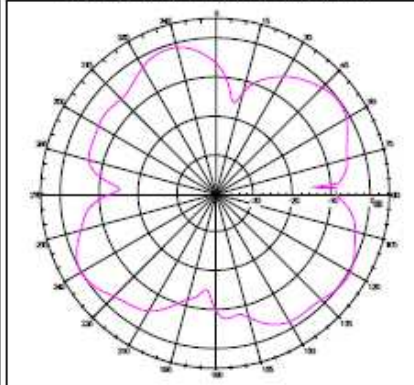


Frequency : 1960.0 MHz

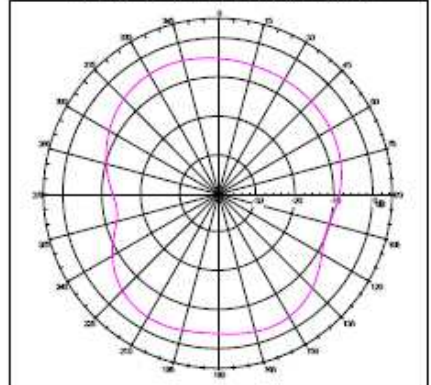
Far-field Power Distribution on X-Z Plane(E-Plane of L3 Pol Sensor)
Gain=1.31 dBi, Total Radiating Efficiency: 47.20% @ 50000 GHz



Far-field Power Distribution on Y-Z Plane(H-Plane of L3 Pol Sensor)
Gain=1.31 dBi, Total Radiating Efficiency: 47.20% @ 50000 GHz

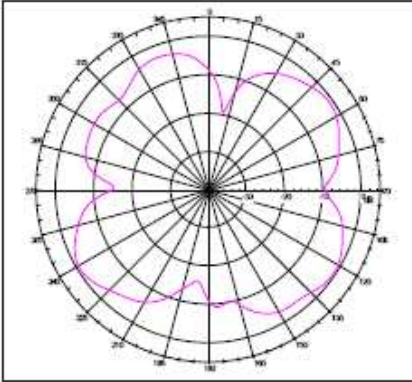


Far-field Power Distribution on X-Y Plane
Gain=1.31 dBi, Total Radiating Efficiency: 47.20% @ 50000 GHz

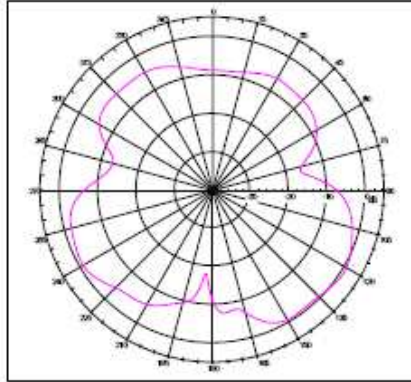


Frequency : 1989.8 MHz

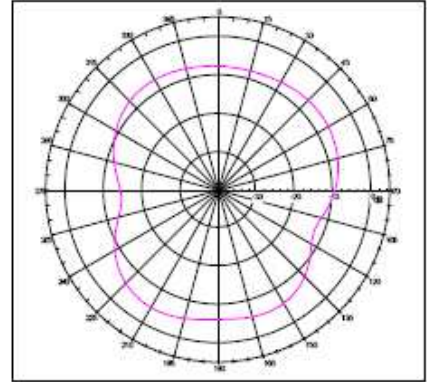
Far-field Power Distribution on Y-Z Plane (H-Plane of L3 Pol Sense)
Gain=0.30 dBi, Total Radiating Efficiency: 36.62% @ 1989.8 MHz



Far-field Power Distribution on X-Z Plane (E-Plane of L3 Pol Sense)
Gain=0.30 dBi, Total Radiating Efficiency: 36.62% @ 1989.8 MHz

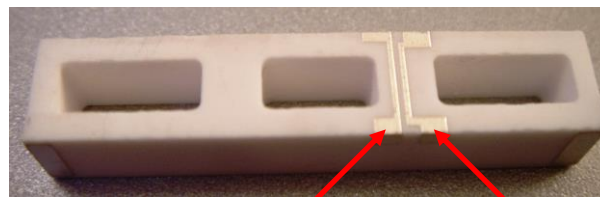
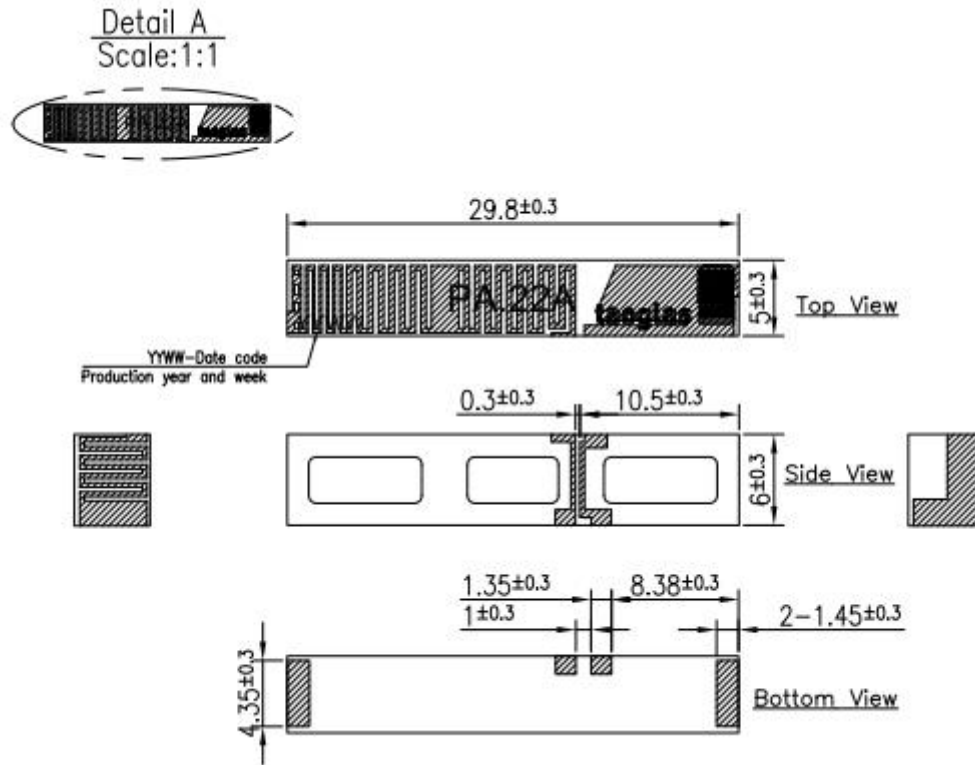


Far-field Power Distribution on X-Y Plane
Gain=0.30 dBi, Total Radiating Efficiency: 36.62% @ 1989.8 MHz



3. Mechanical Dimensions

3.1 PA.22 Antenna



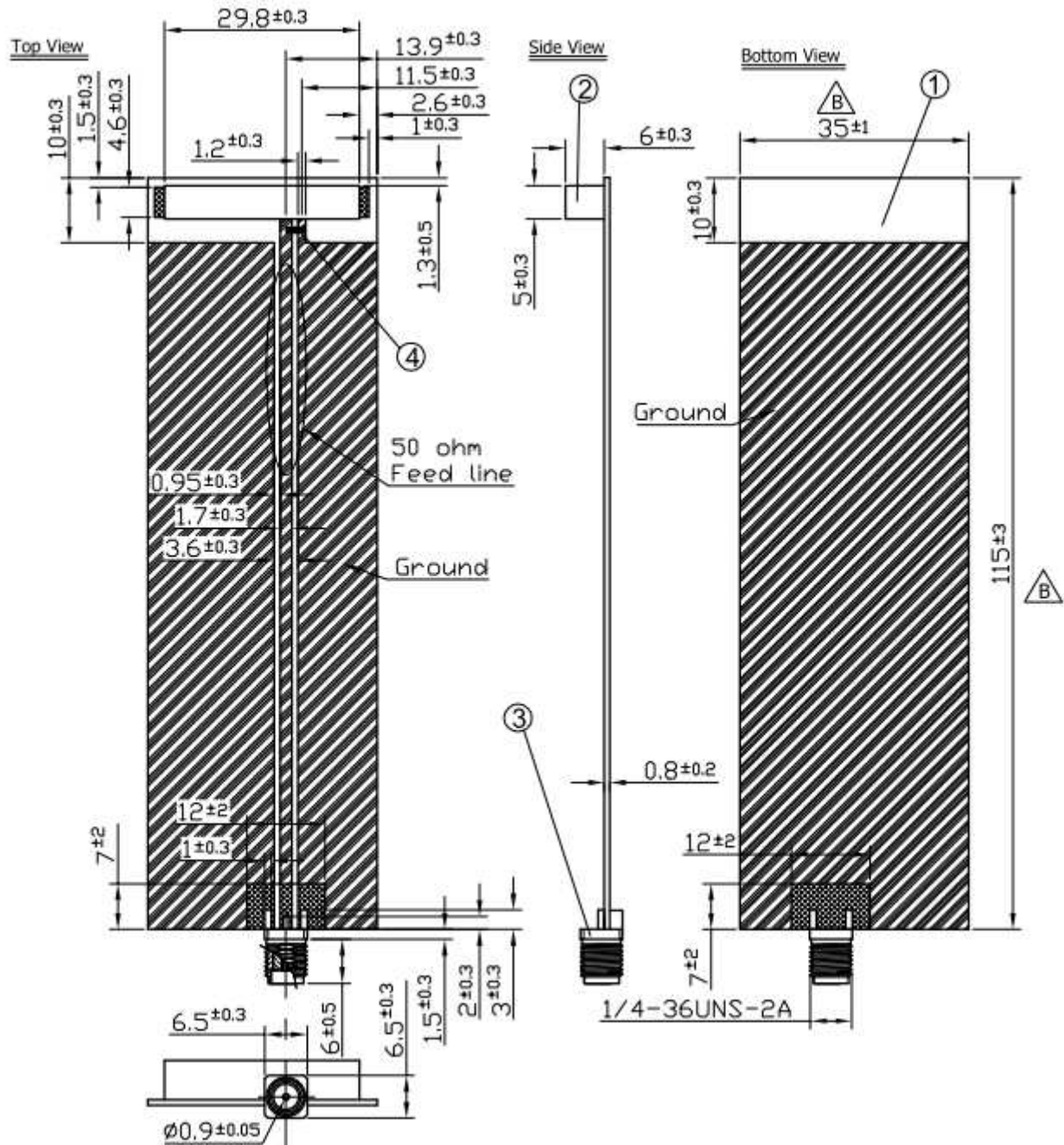
feed to module

to ground






solder pads
(mechanical only)

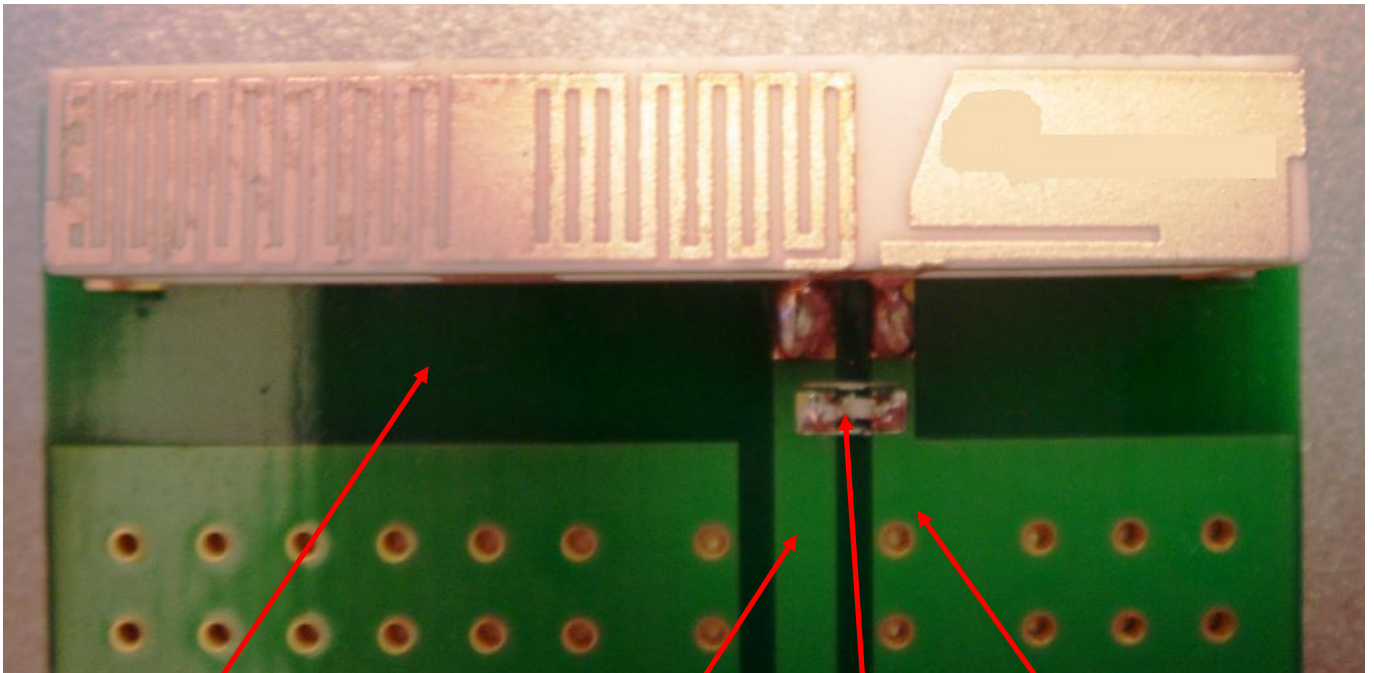
3.2 Evaluation board dimensions



Note:

1. Unique dimensioning according to your PCB
inductor and capacitor values according to you specific device
2. Copper area 
3. Soldered area 
4. Clearance area 

3.3 Recommended layout (as per Taoglas evalution board)

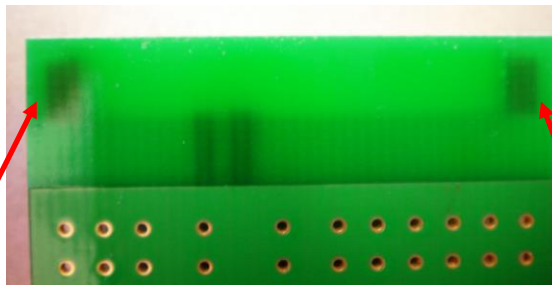


Non metal area
6mm clearance ideally
(minimum 4mm clearance)

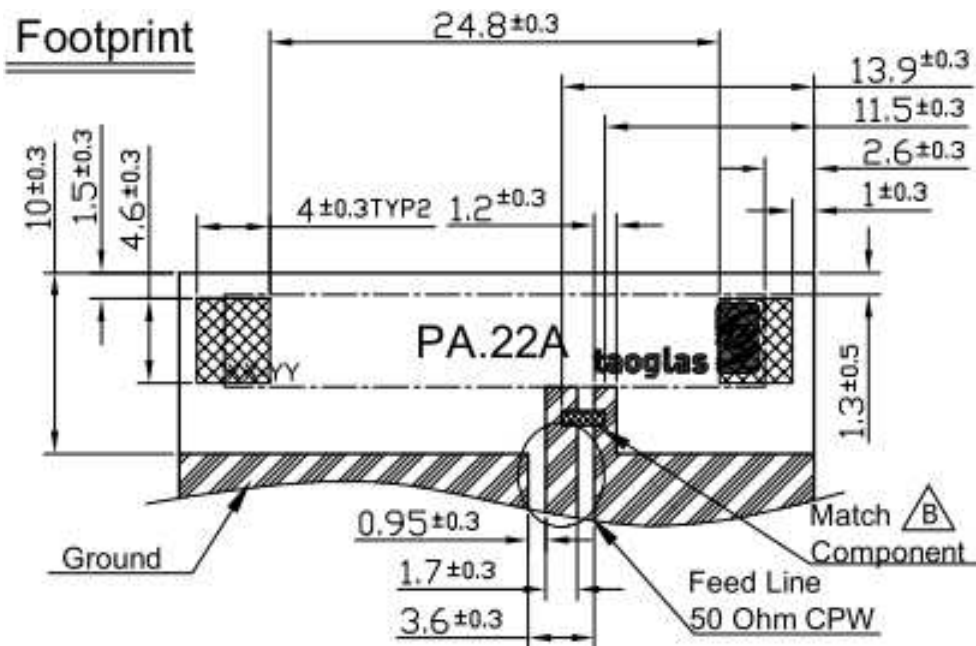
feed to module

4.7nH inductor
For EVB only

to ground

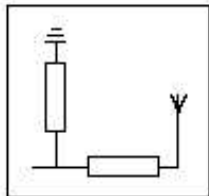


View from underneath board – note solder pads either side – laid out on non metal area
Layout dimensions - Allow 6mm clearance all around if possible (minimum 4mm)

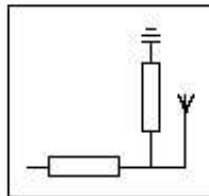


3.4 Recommended Transmission Line and Matching Network

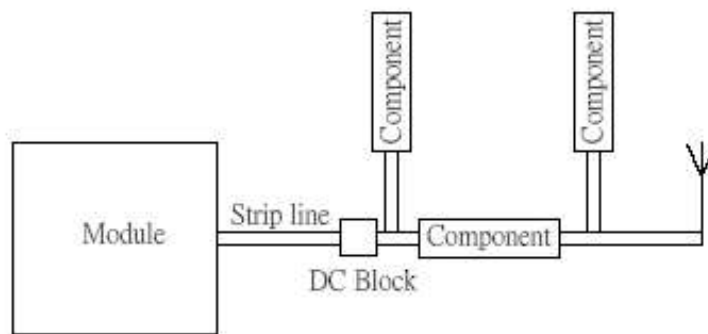
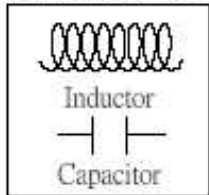
Typical config.1



Typical config.2



Component types

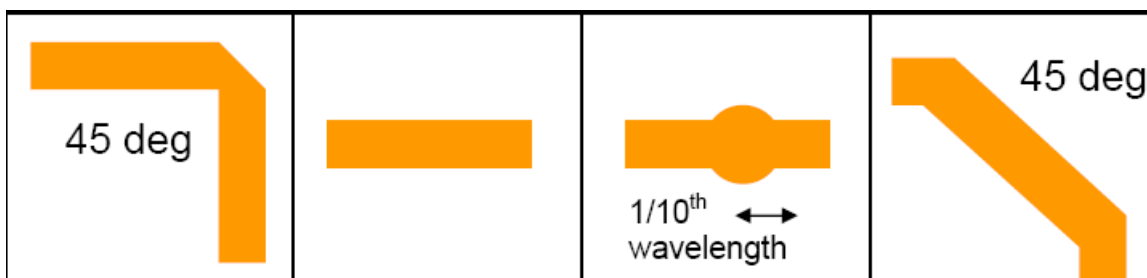


The matching network has to be individually designed using one, two or three components.

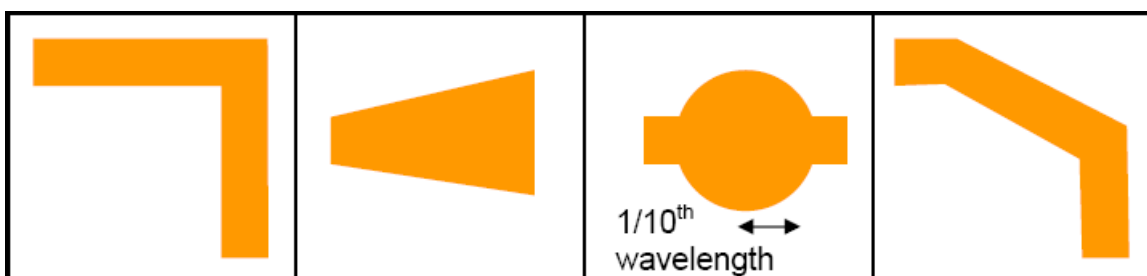
Note: The PA.22 can be made "quad band" with appropriate matching circuit

Guidelines for routing RF when designing a PCB;

1) Good

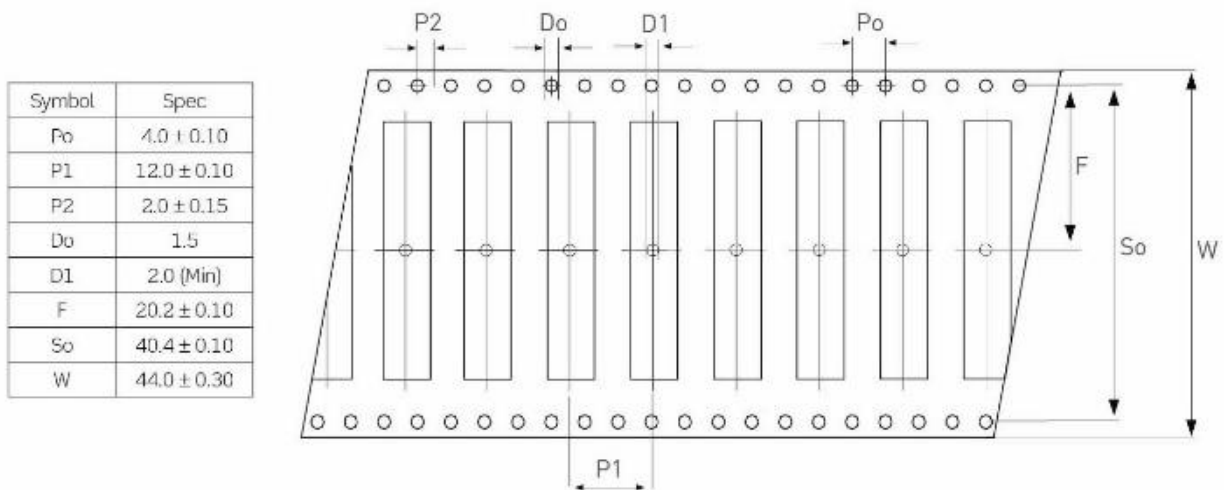
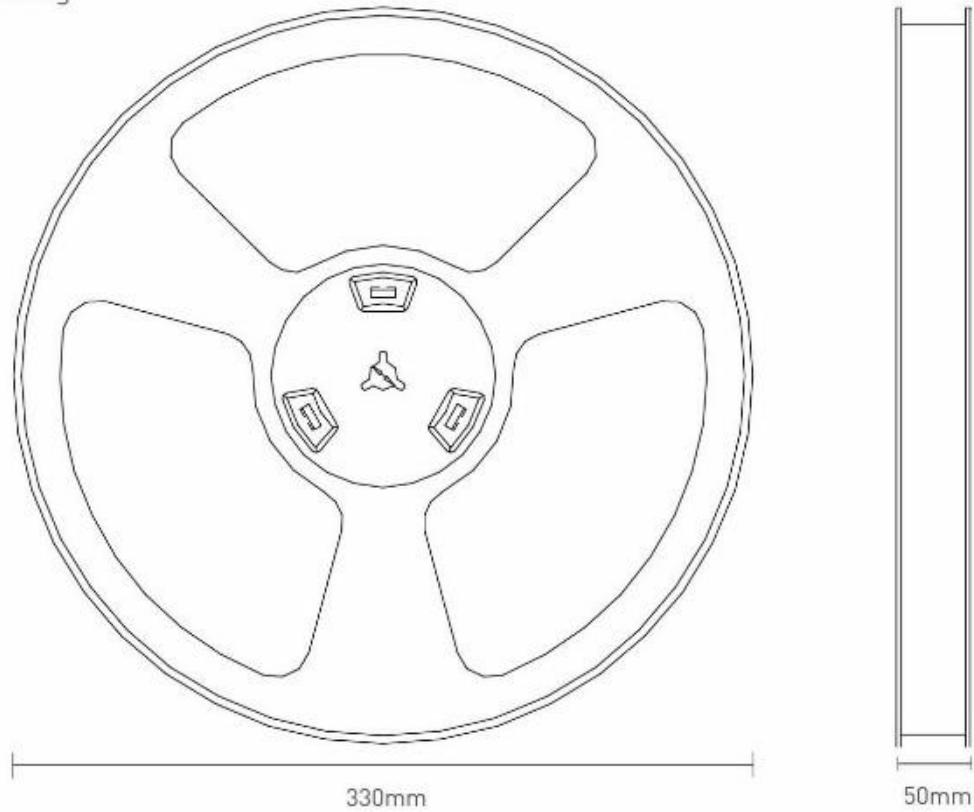


2) Bad

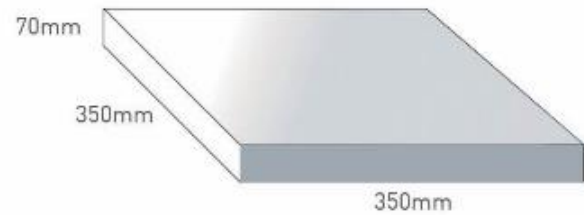


4. Packaging

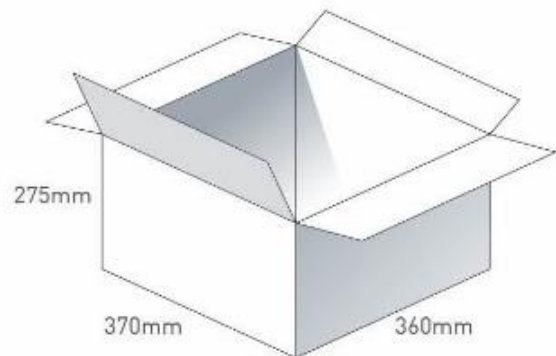
450 pc PA.22.A
1 reel per small inner box
Dimensions - 330*50mm
Weight - 3.3kg



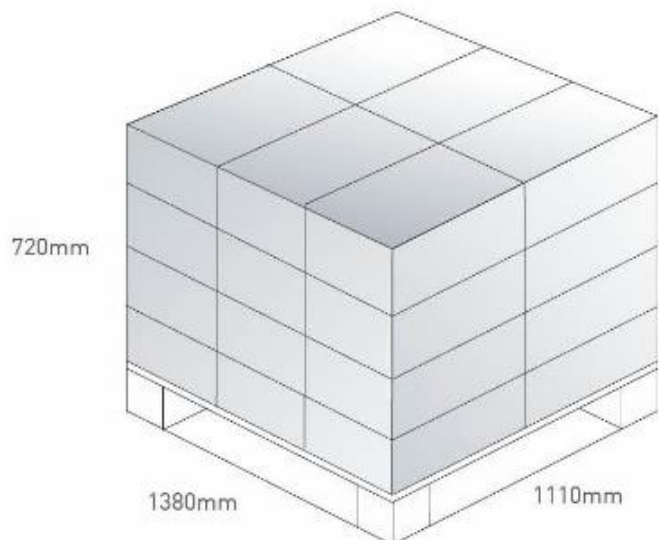
450 pc PA.22.A
1 reel in small inner box
Dimensions - 350*350*70
Weight - 3.6Kg



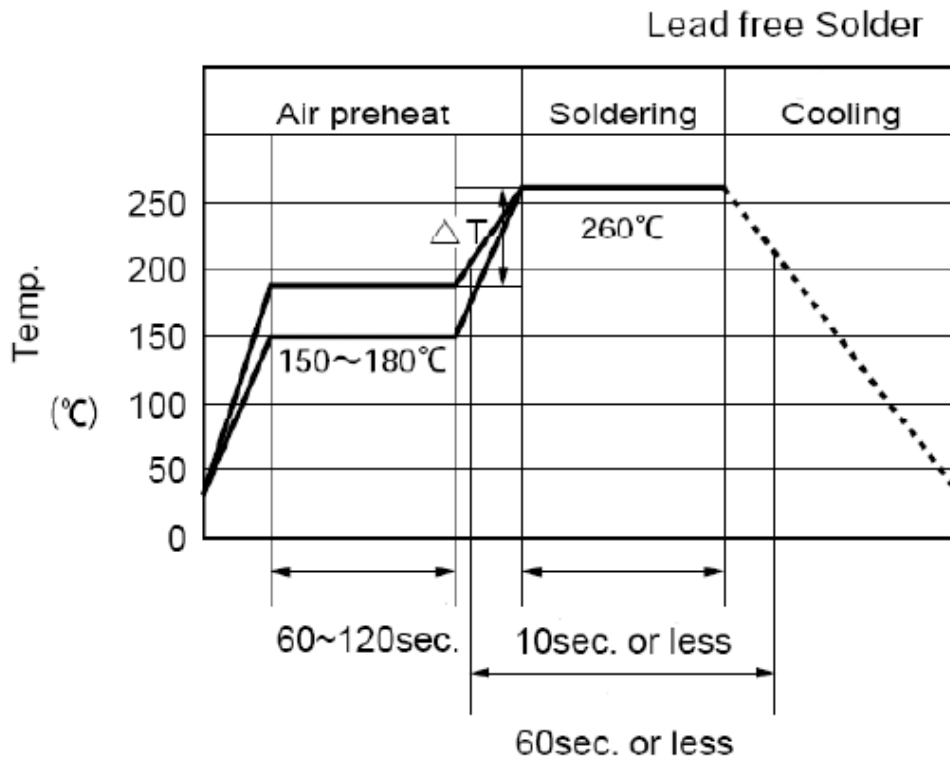
4 boxes / 1800 pcs in one carton
Carton Dimensions - 370*360*275mm
Weight -14.4Kg



Pallet Dimensions 1110*720*1380mm
24 Cartons per Pallet
6 Cartons per layer
4 Layers



5. Recommended Reflow Temperature Profile



(1) Time shown in the above figures is measured from the point when chip surface reaches temperature.

(2) Temperature difference in high temperature part should be within 110°C.

(3) After soldering, do not force cool, allow the parts to cool gradually.

*General attention to soldering:

- High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- for soldering, please refer to the soldering curves above. However, please keep exposure to temperatures exceeding 200°C to under 50 seconds.
- please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.

Cleaning:

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40 kHz max. - Output power: 20W/liter -Cleaning time: 5minutes max.